

**IN THE CLAIMS:**

Please cancel claims 9, 11, 25, and 26 and amend the claims as follows:

1. (Currently Amended) An integrated bevel cleaning (IBC) apparatus, comprising:
  - a transfer position where a substrate is positioned;
  - a rinse position where the substrate is rinsed;
  - an etch position where the edge of the substrate is cleaned;
  - an actuator for positioning the substrate in the transfer position, the rinse position and the etch position; and
  - a plurality of cooperatively movable etchant dispense nozzles coupled to at least one etchant dispensing arm assembly positioned proximate the etch position and rotatably positionable near and away from the substrate, the arm and nozzles being cooperatively configured to dispense an etchant onto the front side and backside of the substrate.
2. (Original) The IBC apparatus of claim 1 further comprising a substrate centering hoop for supporting the substrate in the transfer position.
3. (Original) The IBC apparatus of claim 2 further comprising a substrate centering hoop rinsing nozzle.
4. (Previously Presented) The IBC apparatus of claim 1 further comprising at least one rinsing nozzle located proximate the rinsing position for rinsing at least an edge region of the substrate.
5. (Previously Presented) The IBC apparatus of claim 4 wherein the at least one rinsing nozzle comprises a plurality of rinsing nozzles positioned to rinse the front side and backside of the substrate.

6. (Previously Presented) The IBC apparatus of claim 1 further comprising at least one slit valve located proximate the transfer position.
7. (Previously Presented) The IBC apparatus of claim 1 wherein the actuator comprises a spindle assembly for retaining the substrate and rotating the substrate, and a linear actuator for raising and lowering the spindle assembly.
8. (Previously Presented) The IBC apparatus of claim 7 wherein the spindle assembly comprises a vacuum chuck.
9. (Cancelled)
10. (Currently Amended) The IBC apparatus of claim 1, 9 wherein the etchant is applied to an edge exclusion zone of the substrate.
11. (Cancelled)
12. (Currently Amended) The IBC apparatus of claim 1, 14 wherein the at least one etchant dispensing arm assembly comprises a plurality of etchant dispensing arm assemblies.
13. (Previously Presented) The IBC apparatus of claim 12 wherein the plurality of etchant dispensing arm assemblies are cooperatively coupled for simultaneously rotating the plurality of etchant dispensing arm assemblies into a position near the substrate and away from the substrate.
- Claims 14-22. (Cancelled)
23. (Previously Presented) The IBC apparatus of claim 13 wherein the plurality of etchant dispensing arm assemblies are cooperatively coupled to a single motor for simultaneously rotating the plurality of etchant dispensing arm assemblies.

24. (Currently Amended) An integrated bevel cleaning (IBC) apparatus, comprising:

a transfer position where a substrate is positioned;

a processing position wherein at least one of rinsing and etching is conducted on the substrate;

an actuator for positioning the substrate in the transfer position and the processing position;

a substrate centering hoop for supporting the substrate in the transfer position and a centering hoop rinsing nozzle; and

a plurality of cooperatively movable etchant dispense nozzles configured to dispense an etchant onto the front side and backside of the substrate.

25. (Cancelled)

26. (Cancelled)

27. (Previously Presented) The IBC apparatus of claim 24 further comprising at least one rinsing nozzle located proximate the processing position for rinsing at least an edge region of the substrate.

28. (Previously Presented) The IBC apparatus of claim 27 wherein the at least one rinsing nozzle comprises a plurality of rinsing nozzles positioned to rinse the front side and backside of the substrate.

29. (Previously Presented) The IBC apparatus of claim 24 further comprising at least one slit valve located proximate the transfer position.

30. (Previously Presented) The IBC apparatus of claim 24 wherein the actuator comprises a spindle assembly for retaining the substrate and rotating the substrate, and a linear actuator for raising and lowering the spindle assembly.

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31. (Previously Presented) The IBC apparatus of claim 30 wherein the spindle assembly comprises a vacuum chuck.
32. (Previously Presented) The IBC apparatus of claim 24 wherein the plurality of etchant dispense nozzles are coupled to at least one etchant dispensing arm assembly positioned proximate the processing position to apply etchant to the front side and backside of the substrate.
33. (Previously Presented) The IBC apparatus of claim 32 wherein the etchant is applied to an edge exclusion zone of the substrate.
34. (Previously Presented) The IBC apparatus of claim 32 wherein the at least one etchant dispensing arm assembly is rotatable into a position near the substrate and away from the substrate.
35. (Previously Presented) The IBC apparatus of claim 34 wherein the at least one etchant dispensing arm assembly comprises a plurality of etchant dispensing arm assemblies.
36. (Previously Presented) The IBC apparatus of claim 35 wherein the plurality of etchant dispensing arm assemblies are cooperatively coupled for simultaneously rotating the plurality of etchant dispensing arm assemblies into a position near the substrate and away from the substrate.
37. (Previously Presented) The IBC apparatus of claim 36 wherein the plurality of etchant dispensing arm assemblies are cooperatively coupled to a single motor for simultaneously rotating the plurality of etchant dispensing arm assemblies.